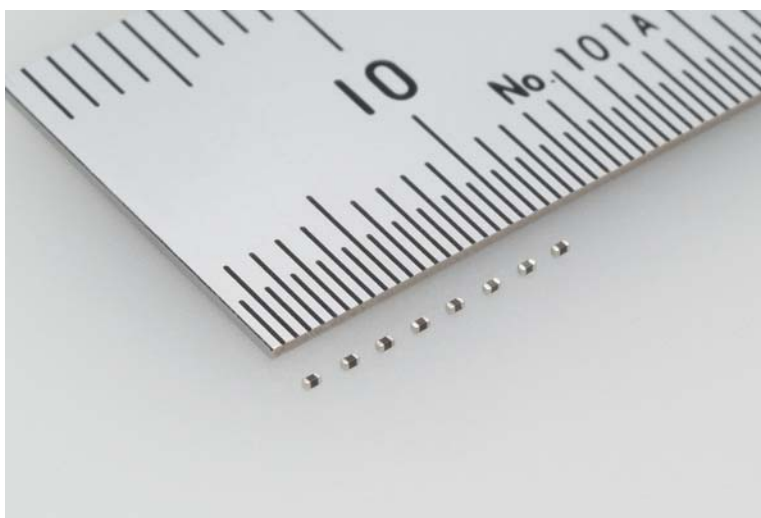


Taiyo Yuden: Launching EIA0201 Size Multilayer Chip Ferrite Beads for Power Circuits

**—Use of Advanced Multilayer and Printing Technologies Shrinks Chip
Surface Area by 64%—**



Taiyo Yuden Co., Ltd. announces sale of the EIA0201 size multilayer chip ferrite bead BKP0603 (0.6x0.3x0.3mm), which will reduce power circuit noise in mobile phones and other mobile equipment. Compared with the previous EIA0402 size BKP1005 (1.0x0.5x0.5mm), the chip surface area has been reduced by 64%.

This product responds to demands for the smaller multilayer chip ferrite beads for power circuits that serve for both multiple functionality and more compactness in mobile phones and other mobile equipment, by achieving a rated current of 1.0A and a Rdc of 65m Ω in the 0201 size (impedance 22 Ω).

Mass production is to commence in May 2008, at a sample price of 5 yen per unit.

The mobile phone market is expanding everywhere all over the world, and the trend is toward more compact size and multiple functionality. With the trend to multiple functionality, the number of IC chips used per phone has increased, and power supply circuits have increasingly been mounted on each IC chip to make power use more efficient toward the goal of reducing power consumption. However, increasing the number of power supply circuits tends to increase the product's size. As a result, there have been demands to reduce the size of the main components within the DC-DC converters, or the power supply circuits mounted on the equipment, as a way to forestall this tendency. However, since the multilayer chip ferrite beads used to reduce noise in the DC-DC converter decline in rated current and Rdc performance as they become smaller in size, and thereby become unable to

handle large current, they were an obstacle toward achievement of the desired characteristics at the more compact size. At this point, Taiyo Yuden made further advances in its multilayer and printing technologies to achieve multilayer chip ferrite beads in the EIA0201 size (0.6x0.3x0.3mm), a reduction of 64% in chip surface area from the previous EIA0402 size (1.0x0.5x0.5mm).

The BKP0603 line-up is as follows.

Part Number	Impedance [Ω]	Rdc [Ω]	Rated Current [A] max
BKP0603HS220	22	0.065	1.0
BKP0603HS330	33	0.070	1.0